

Electronic Patent Application Fee Transmittal

Application Number:	10824111			
Filing Date:	14-Apr-2004			
Title of Invention:	Wafer-level electronic modules with integral connector contacts and methods of fabricating the same			
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Filer:	Robert M. Meeks/Candi Riggs			
Attorney Docket Number:	5649-1279			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 1 month with \$0 paid	1251	1	120	120

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	790	790
Total in USD (\$)				910